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interconnections required for high performance circuits due to the possible electrical shorting between contacts. In addition, the random dispersion of particles requires patterned masking of the circuit layers to prevent shorting between layers.

A version marked up to show changes made to the specification relative to the previous version of the specification is attached.

In the Claims:

Please amend claims 37 and 38 as follows:

37. (amended) A method for forming an electronic circuit element, the method comprising:

providing a precursor element including a first insulating layer and a first conductor attached to said first insulating layer, said first insulating layer having a first surface, at least a portion of said first surface defining a first surface plane and said precursor element having a surface, said precursor element surface including said first surface of said first insulating layer;

placing a conducting member onto the precursor element and into electrical communication with said first conductor, said conducting member including a surface and protruding to an apex at a first level, said first level at least beyond said first surface plane;

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said precursor element surface and said conducting member surface defining a major surface of a predetermined shape;

placing a second insulating layer including an adhesive onto substantially all of said major surface, said second insulating layer including oppositely disposed portions extending laterally from said conducting member along said first surface of said first insulating layer, said second insulating layer at said oppositely disposed portions extending to a second level, said first level beyond said second level; and

removing at least a portion of said second insulating layer proximate the apex of said conducting member.

38. (amended) An electronic circuit element comprising:

a first insulating layer having at least one surface, at least a portion of said surface defining a first surface plane;

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at least one conductor along at least a portion of said at least one surface,
a conducting member in communication with said at least one conductor, said
conducting member protruding to an apex at a first level, said first level beyond
said first surface plane, said conducting member including a surface; said surface
of said first insulating layer, said at least one conductor, and said surface of said
conducting member, defining a major surface of a predetermined shape;
a second insulating layer along at least a portion of said major surface whereby at least a
portion of said conducting member remains exposed, said second insulating layer
including portions extending laterally from said conducting member along said
first insulating layer, said laterally extending portions extending from said first
surface plane to a second level, said second level less than said first level wherein
said second insulating layer includes an adhesive.

Please cancel claim 43.

A version with markings to show changes made in the claim(s) relative to the
previous version of the claim(s) is attached.